



STS2622A

SamHop Microelectronics Corp.

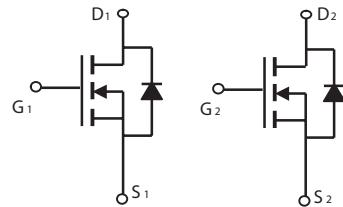
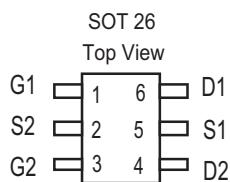
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Dual N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
VDSS	ID	RDS(ON) (mΩ) Max
20V	3.4A	60 @ VGS=4.5V
		90 @ VGS=2.5V

FEATURES

- Super high dense cell design for low RDS(ON).
- Rugged and reliable.
- Surface Mount Package.



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter		Limit	Units
V_{DS}	Drain-Source Voltage		20	V
V_{GS}	Gate-Source Voltage		± 12	V
I_D	Drain Current-Continuous ^a	$T_A=25^\circ\text{C}$	3.4	A
		$T_A=70^\circ\text{C}$	2.7	A
I_{DM}	-Pulsed ^b		13.5	A
P_D	Maximum Power Dissipation ^a	$T_A=25^\circ\text{C}$	1.25	W
		$T_A=70^\circ\text{C}$	0.8	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range		-55 to 150	°C

THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient ^a	100	°C/W
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ELECTRICAL CHARACTERISTICS ($T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	20			V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=16V, V_{GS}=0V$			1	μA
I _{GSS}	Gate-Body Leakage Current	$V_{GS} = \pm 12V, V_{DS}=0V$			± 100	nA
ON CHARACTERISTICS						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	0.78	1.5	V
R _{D(S(ON))}	Drain-Source On-State Resistance	$V_{GS}=4.5V, I_D=3.4A$		48	60	m ohm
		$V_{GS}=2.5V, I_D=2.8A$		67	90	m ohm
g _{FS}	Forward Transconductance	$V_{DS}=5V, I_D=3.4A$		9.5		S
DYNAMIC CHARACTERISTICS ^c						
C _{iss}	Input Capacitance	$V_{DS}=10V, V_{GS}=0V$ $f=1.0MHz$		230		pF
C _{oss}	Output Capacitance			55		pF
C _{rss}	Reverse Transfer Capacitance			35		pF
SWITCHING CHARACTERISTICS ^c						
t _{D(ON)}	Turn-On Delay Time	$V_{DD}=10V$ $I_D=1A$ $V_{GS}=4.5V$ $R_{GEN}=6\text{ ohm}$		7		ns
t _r	Rise Time			7.2		ns
t _{D(OFF)}	Turn-Off Delay Time			13.5		ns
t _f	Fall Time			1.6		ns
Q _g	Total Gate Charge	$V_{DS}=10V, I_D=3.4A,$ $V_{GS}=4.5V$		4.5		nC
Q _{gs}	Gate-Source Charge			0.9		nC
Q _{gd}	Gate-Drain Charge			1.9		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
V _{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=1A$		0.8	1.2	V
Notes						
a.Surface Mounted on FR4 Board, $t \leq 10\text{sec}$.						
b.Pulse Test:Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.						
c.Guaranteed by design, not subject to production testing.						

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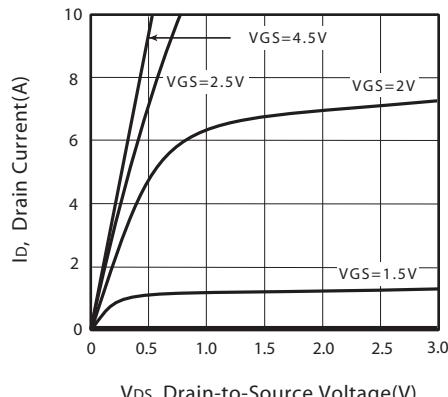


Figure 1. Output Characteristics

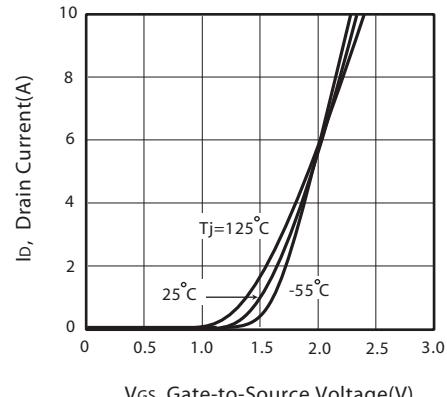


Figure 2. Transfer Characteristics

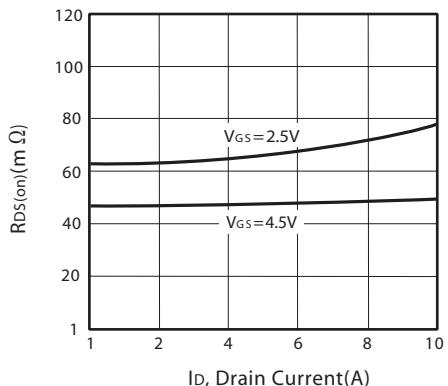


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

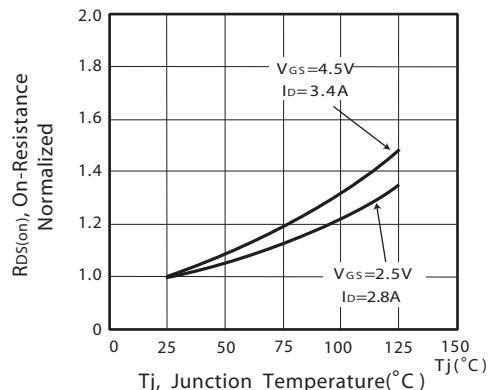


Figure 4. On-Resistance Variation with Drain Current and Temperature

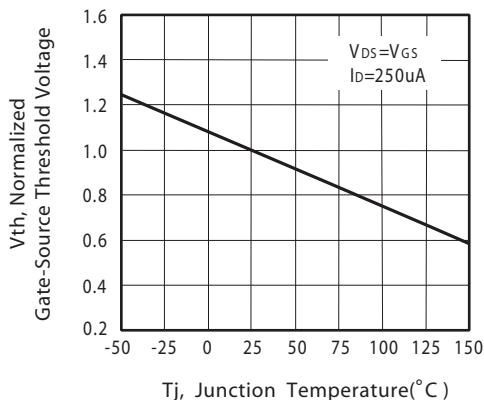


Figure 5. Gate Threshold Variation with Temperature

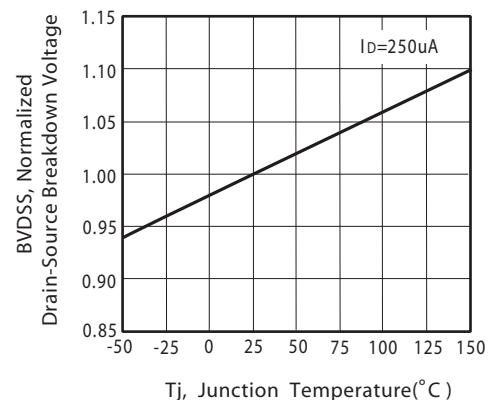


Figure 6. Breakdown Voltage Variation with Temperature

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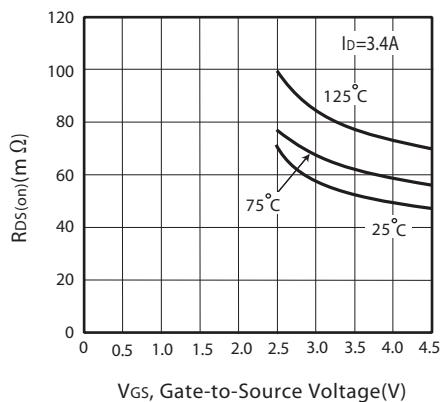


Figure 7. On-Resistance vs. Gate-Source Voltage

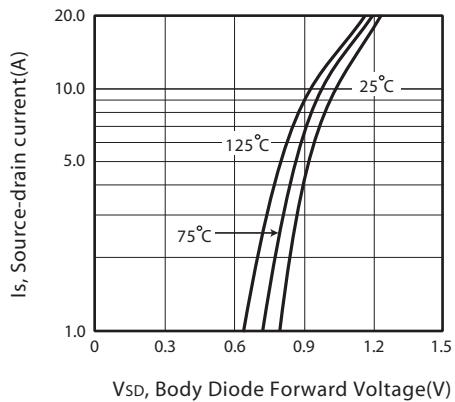


Figure 8. Body Diode Forward Voltage Variation with Source Current

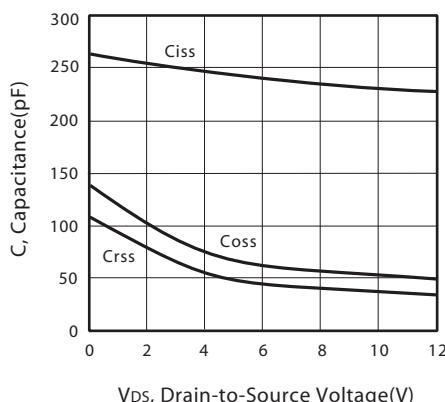


Figure 9. Capacitance

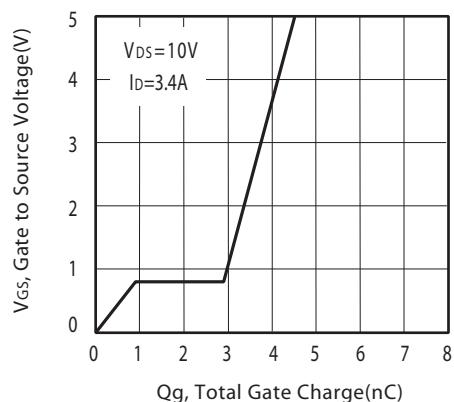


Figure 10. Gate Charge

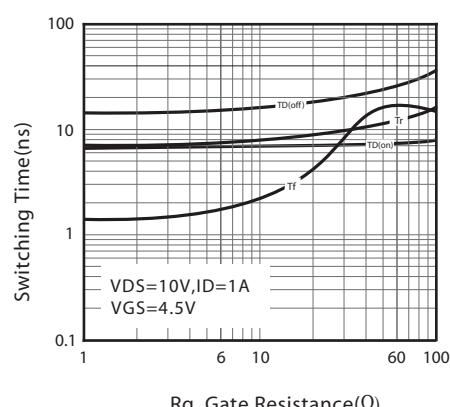


Figure 11. switching characteristics

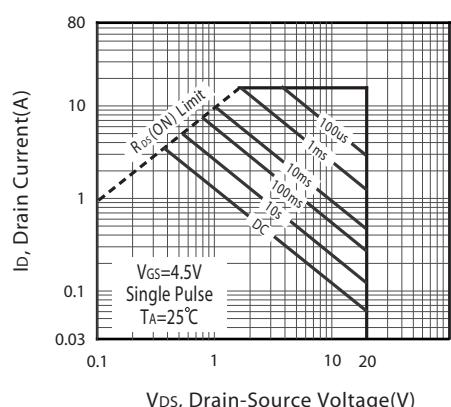
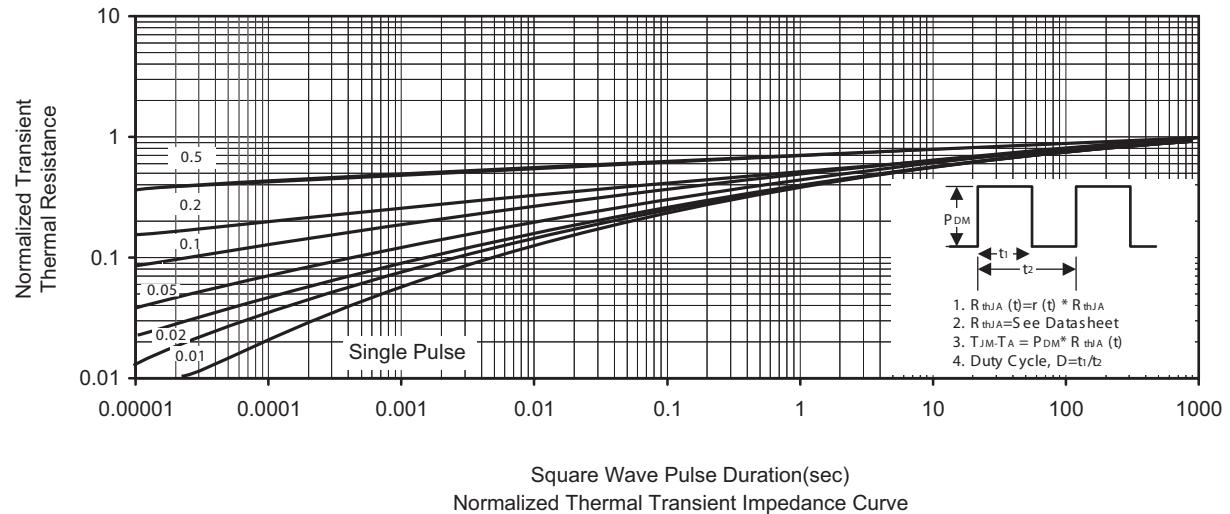


Figure 12. Maximum Safe Operating Area

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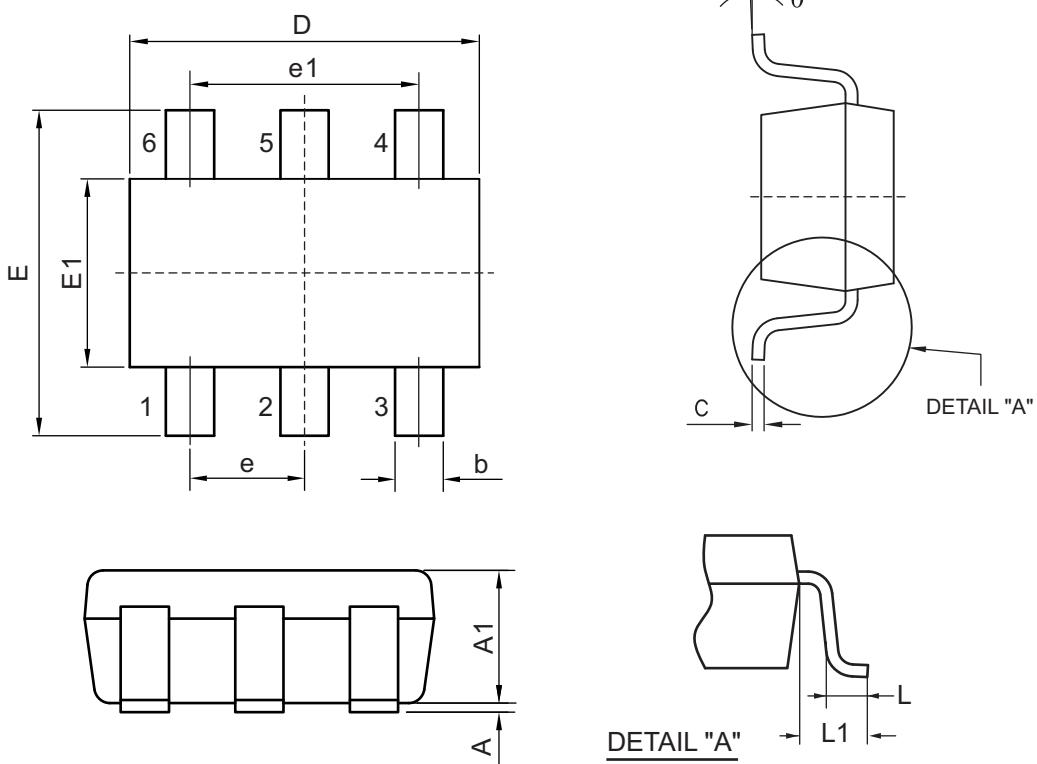


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PACKAGE OUTLINE DIMENSIONS

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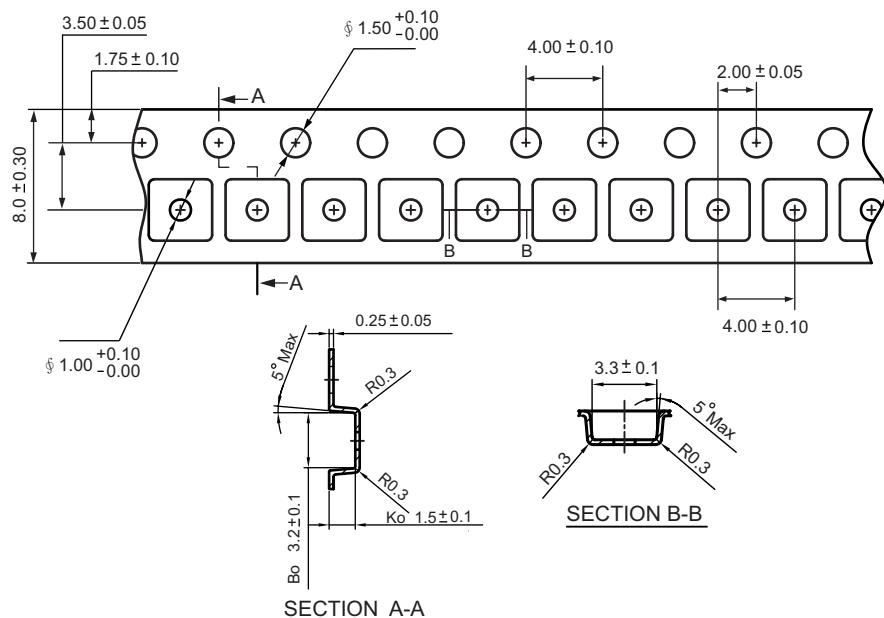
SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
D	2.700	3.100	0.106	0.122
E	2.500	3.100	0.098	0.122
E1	1.400	1.800	0.055	0.071
e	0.950 REF.		0.037 REF.	
e1	1.900 REF.		0.075 REF.	
b	0.300	0.500	0.012	0.020
C	0.090	0.200	0.004	0.008
A	0.000	0.130	0.000	0.005
A1	0.700	1.120	0.028	0.044
L	0.300	0.550	0.012	0.022
L1	0.350	0.800	0.014	0.031
θ	0°	10°	0°	10°

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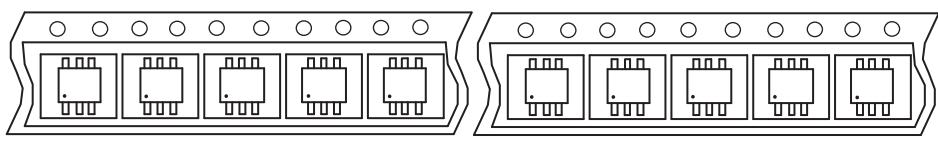
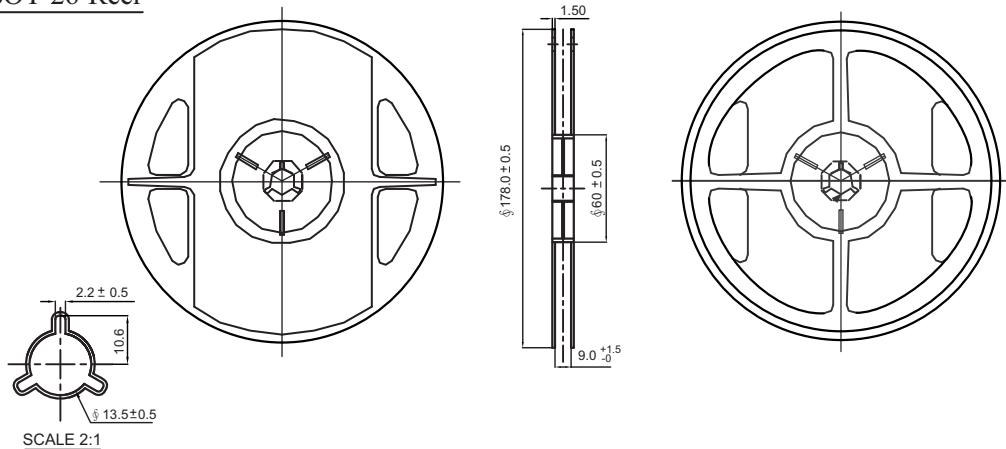
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SOT 26 Tape and Reel Data

SOT 26 Carrier Tape



SOT 26 Reel



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